

FIG.1

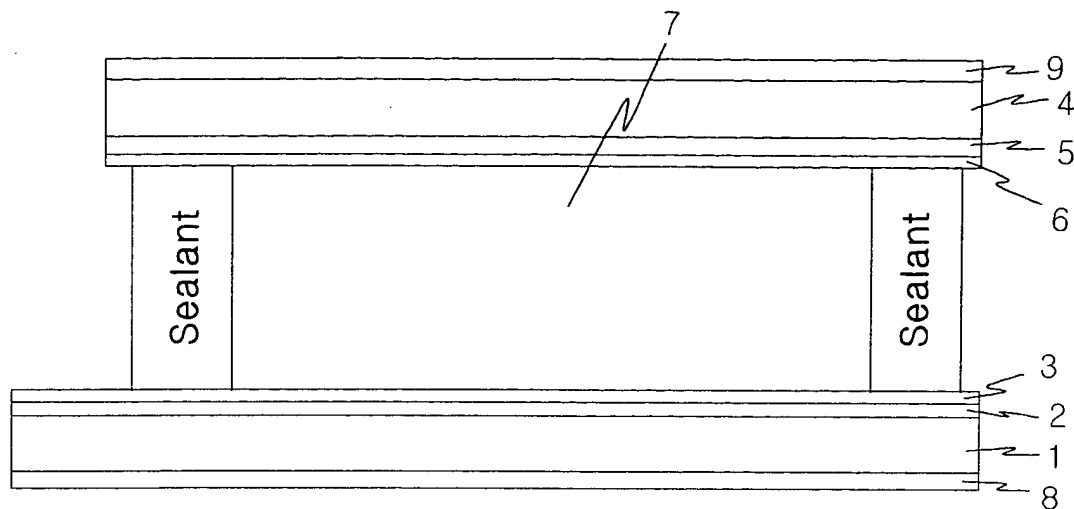


FIG.2

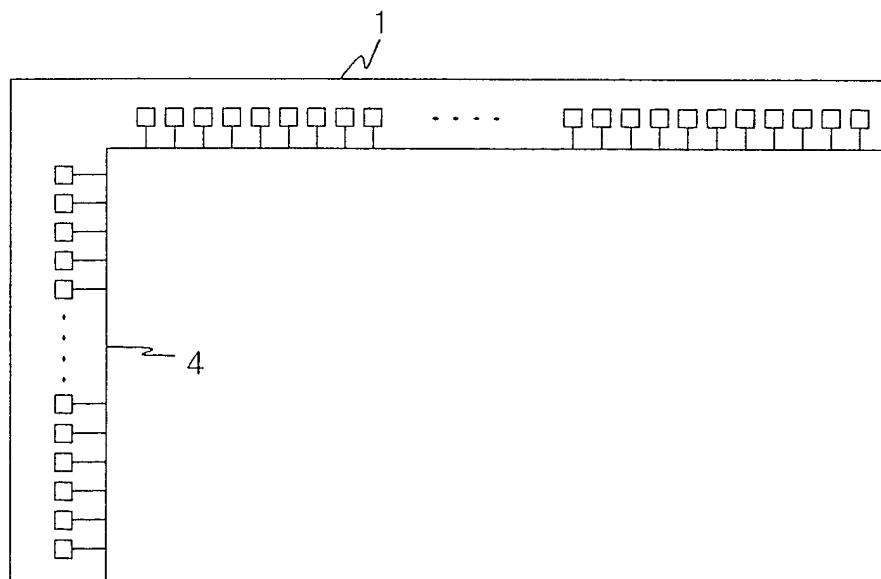


FIG.3

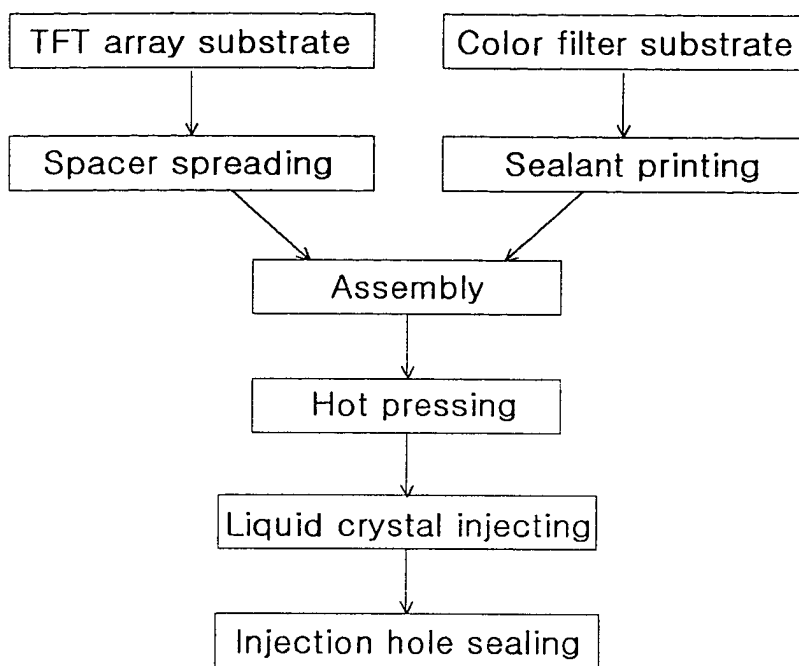
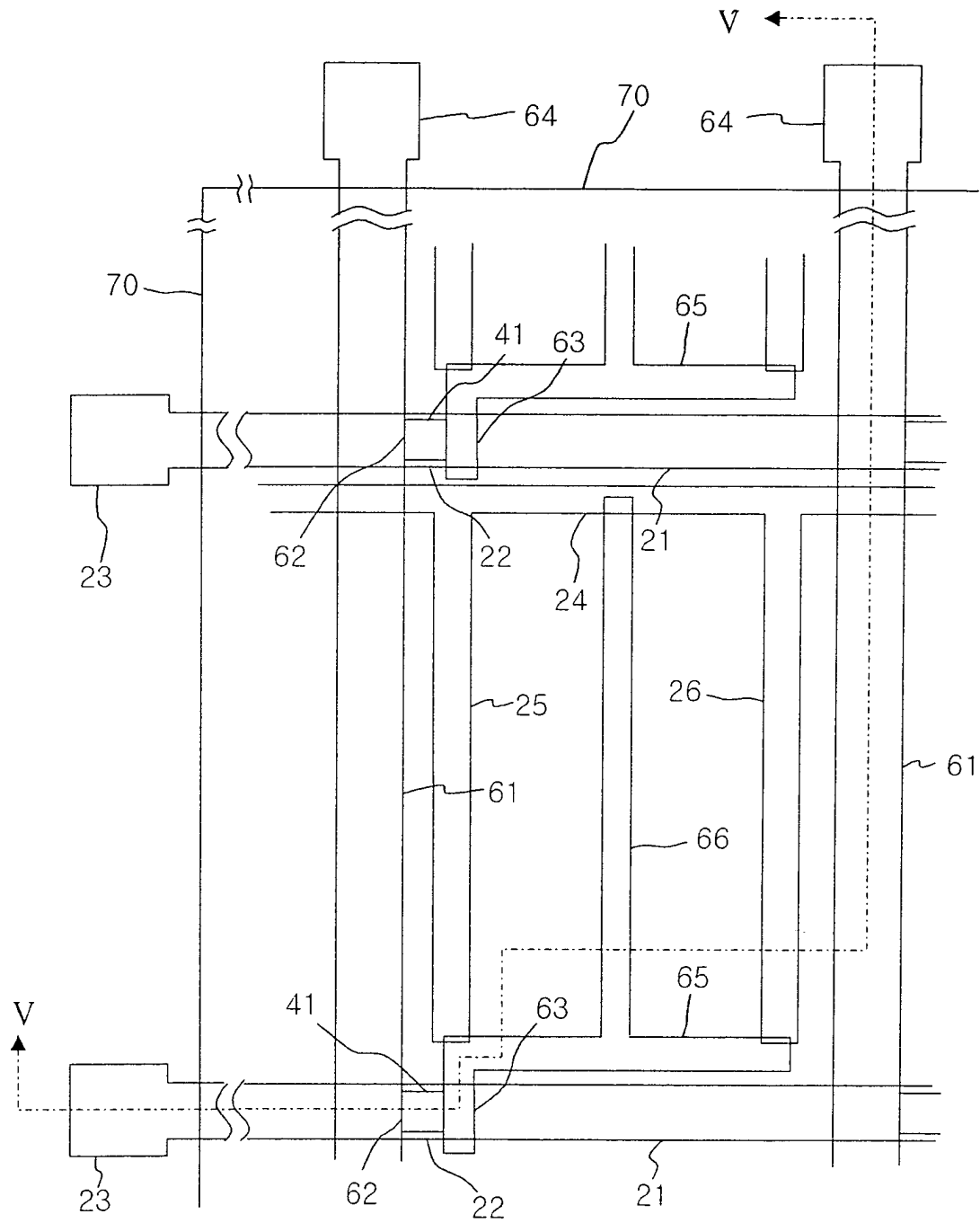


FIG.4



This diagram shows a cross-sectional view of a semiconductor device. It features a substrate 10 with a series of vertical layers and structures. Key components include:

- 21: A central vertical layer or channel.
- 22: A layer adjacent to 21.
- 23: A bottom layer or contact.
- 24: A layer above 21.
- 26: A layer above 24.
- 30: A top layer or contact.
- 41: Multiple small rectangular features or contacts.
- 51: A layer or region.
- 52: A layer or region.
- 61: A layer or region.
- 62: A layer or region.
- 63: A layer or region.
- 64: A layer or region.
- 65: A layer or region.
- 66: A layer or region.
- 70: A top surface or layer.

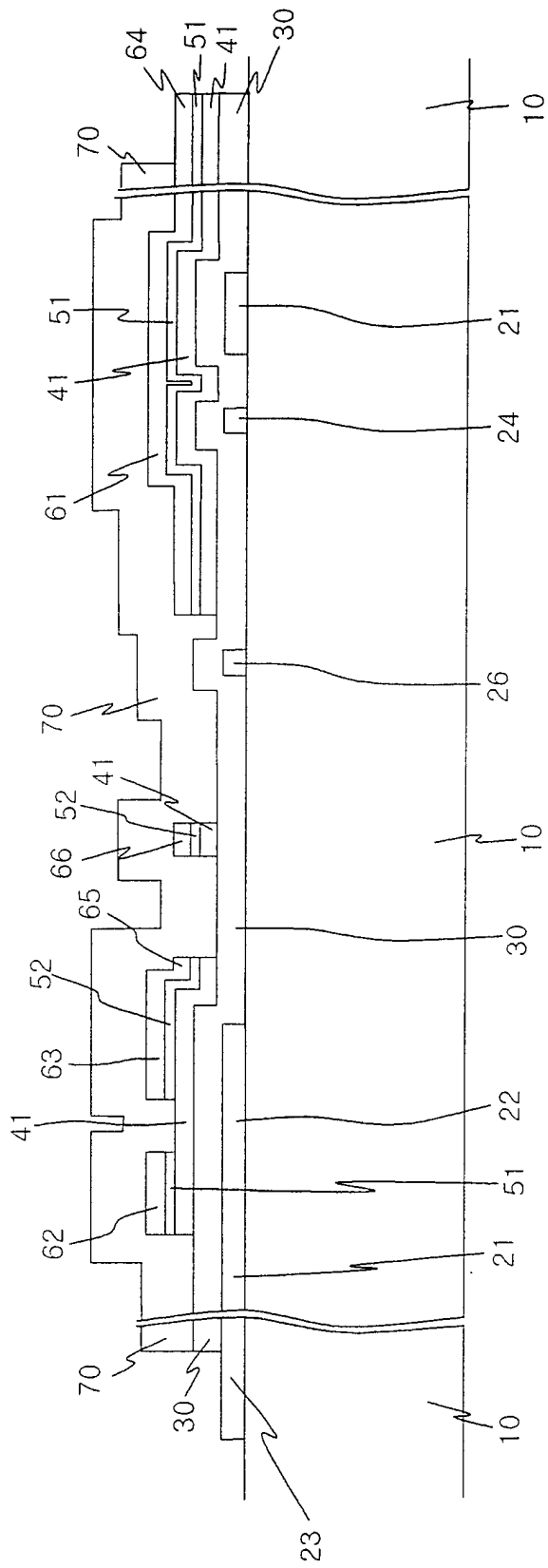


FIG.6A

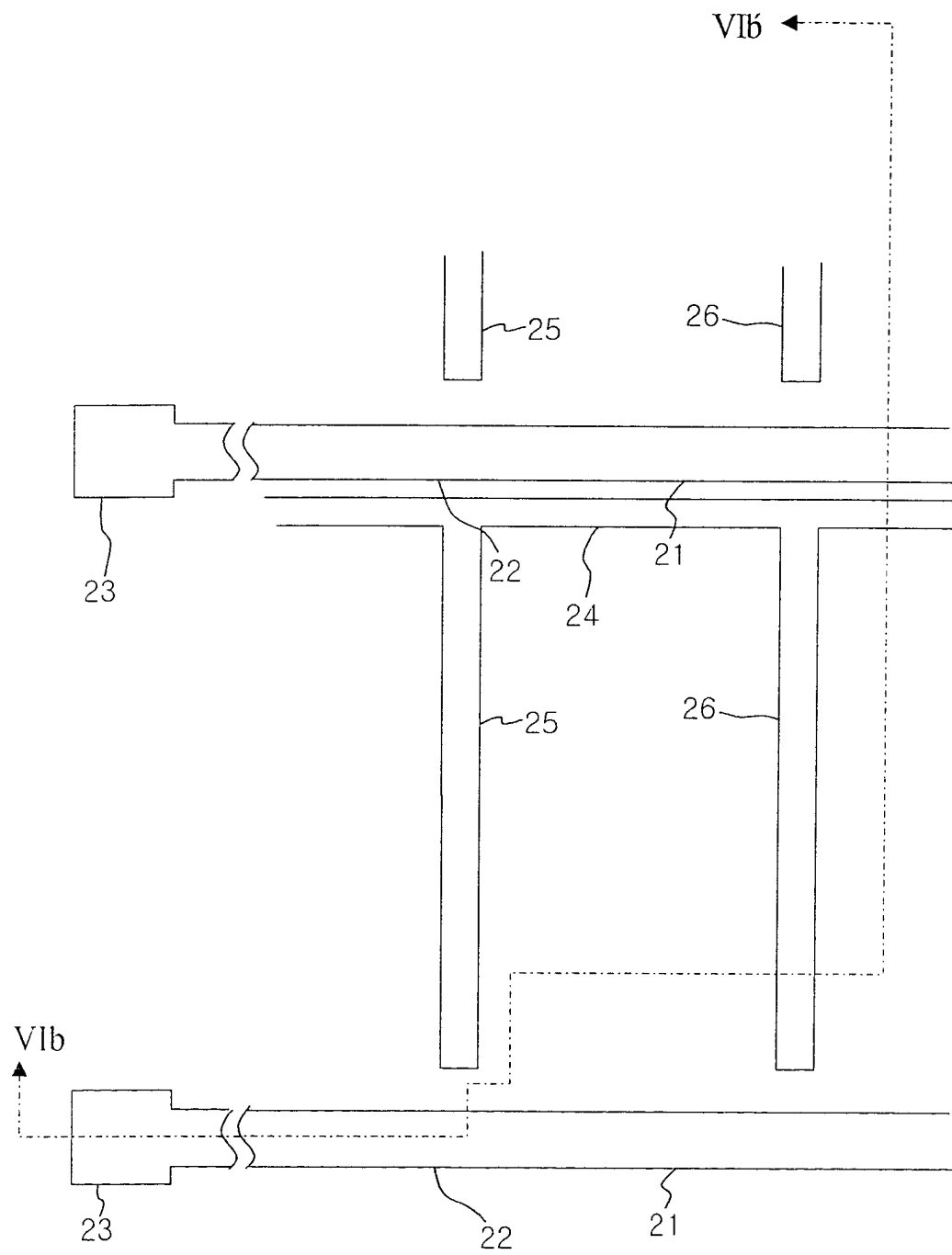


FIG.6B

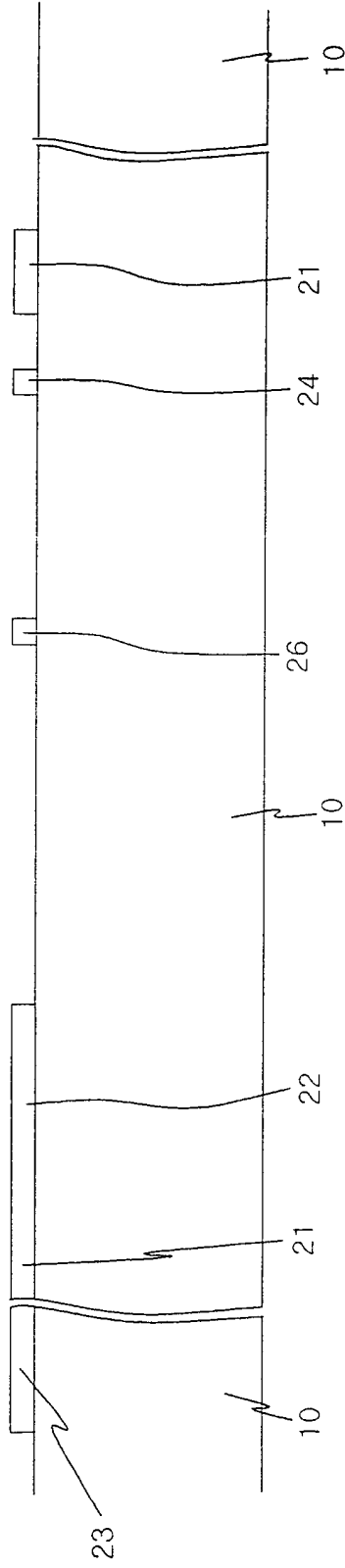


FIG. 7A

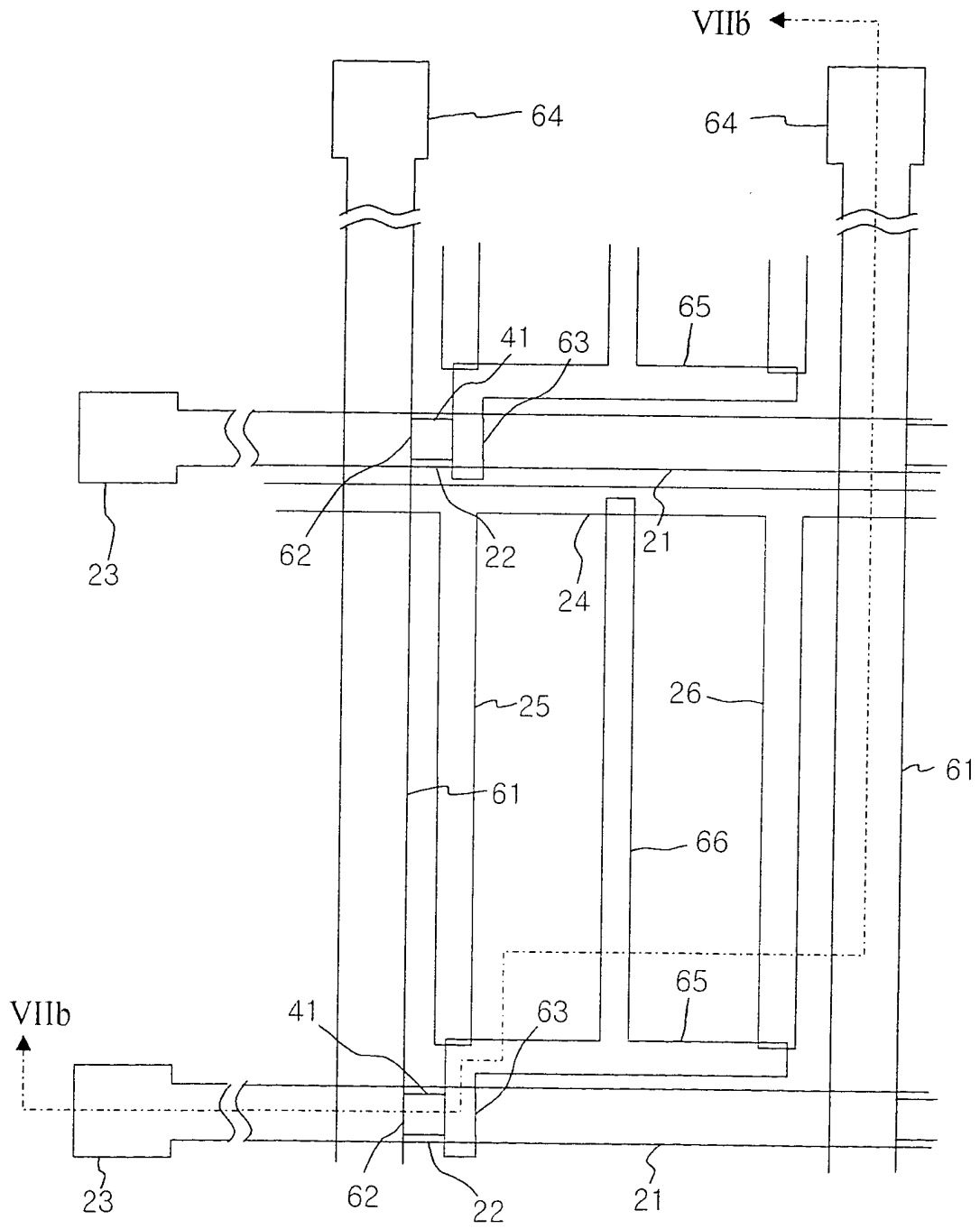


FIG.7B

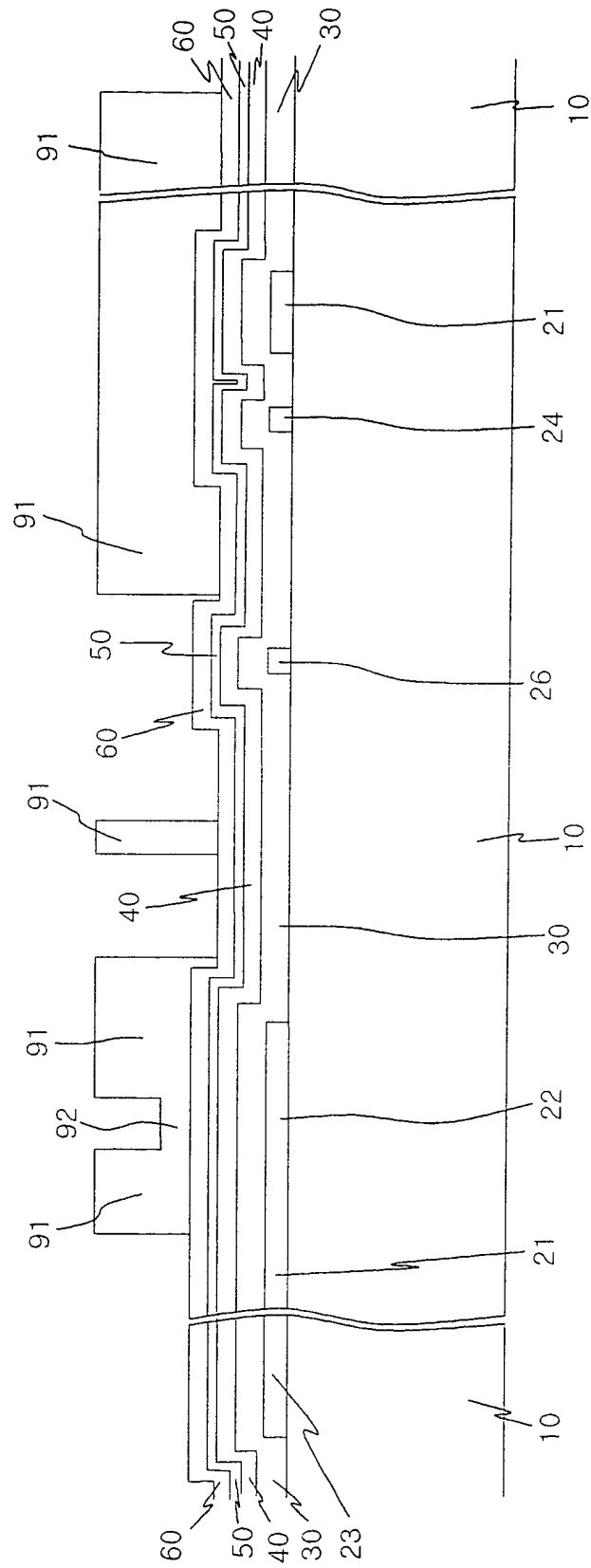


FIG.8

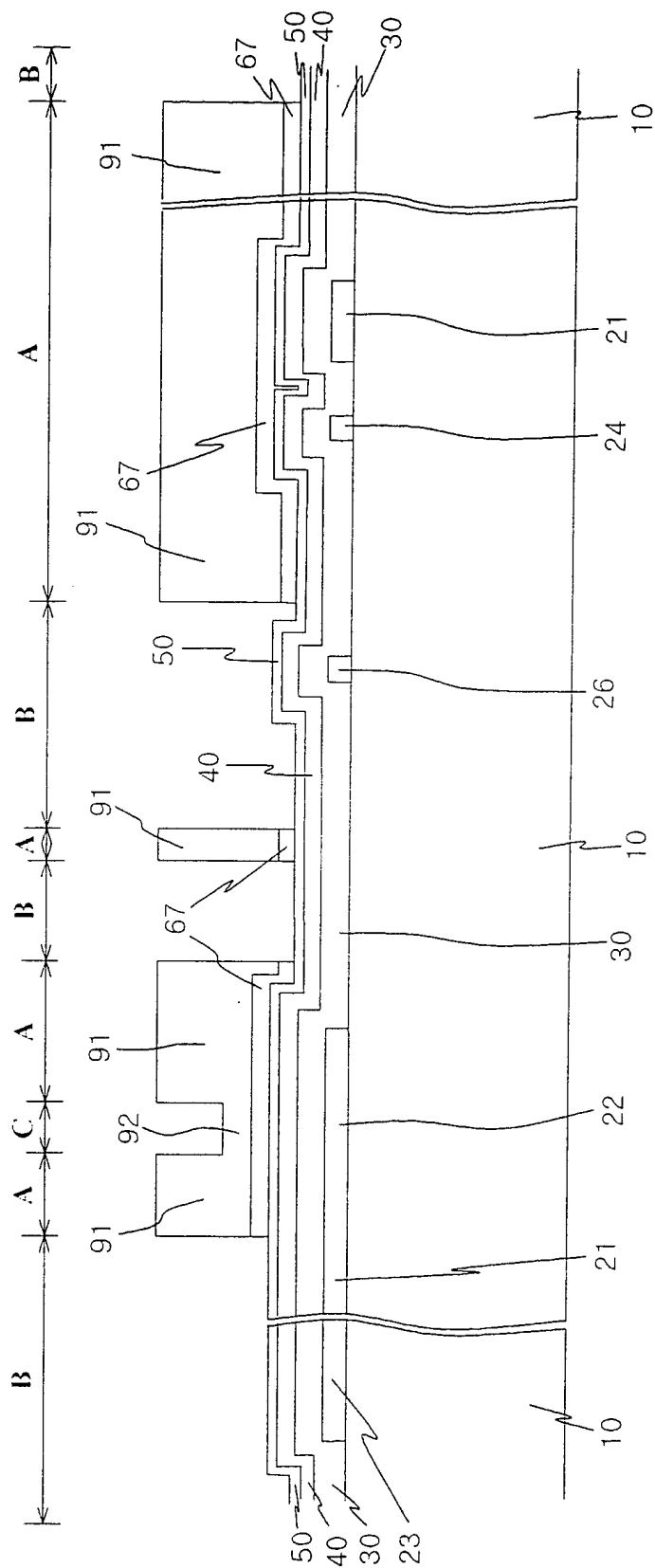


FIG.9

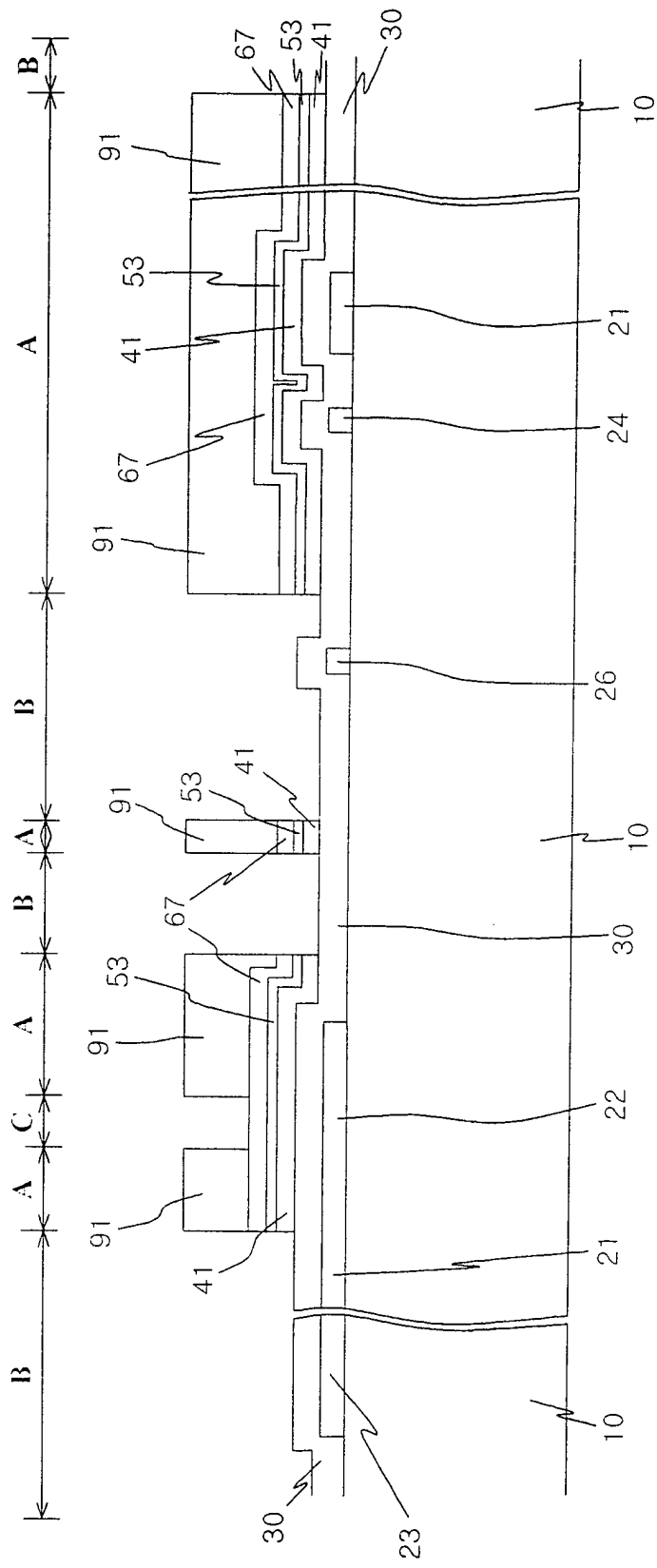


FIG.10

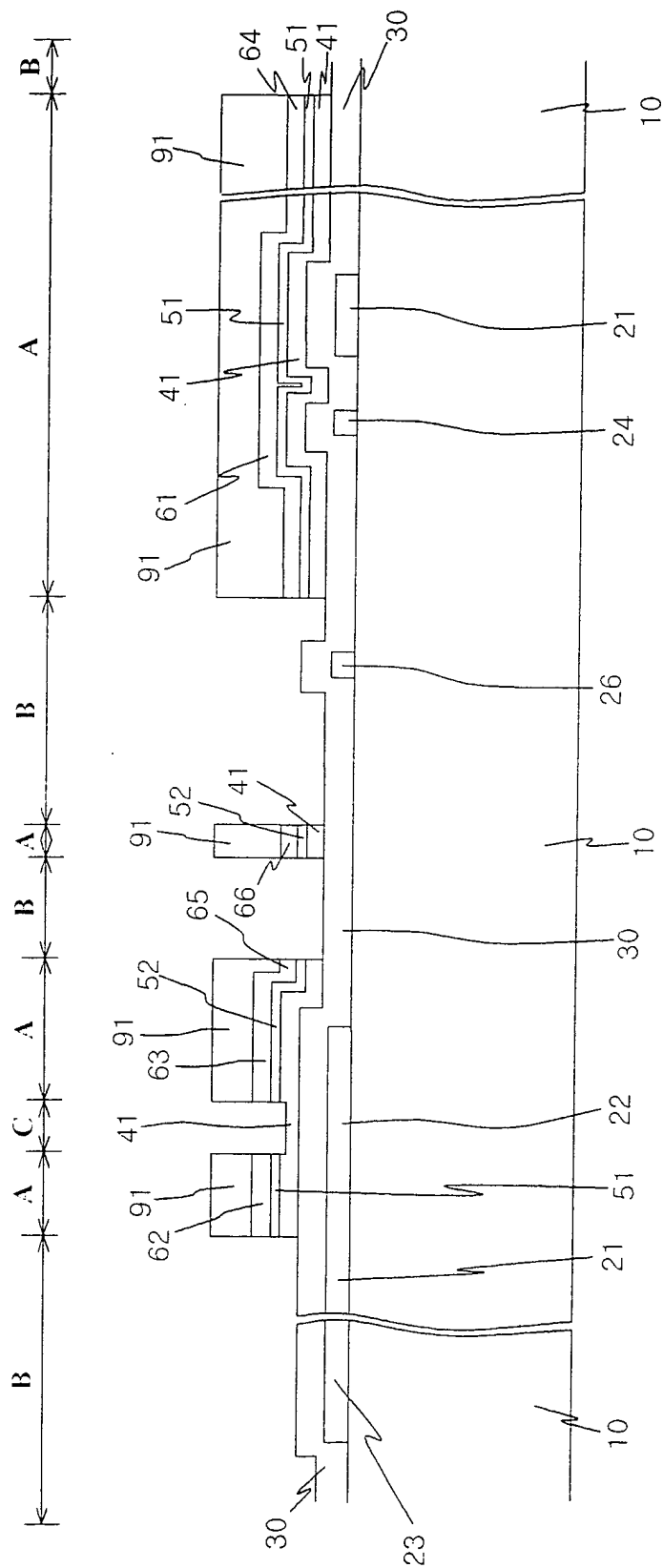


FIG.11

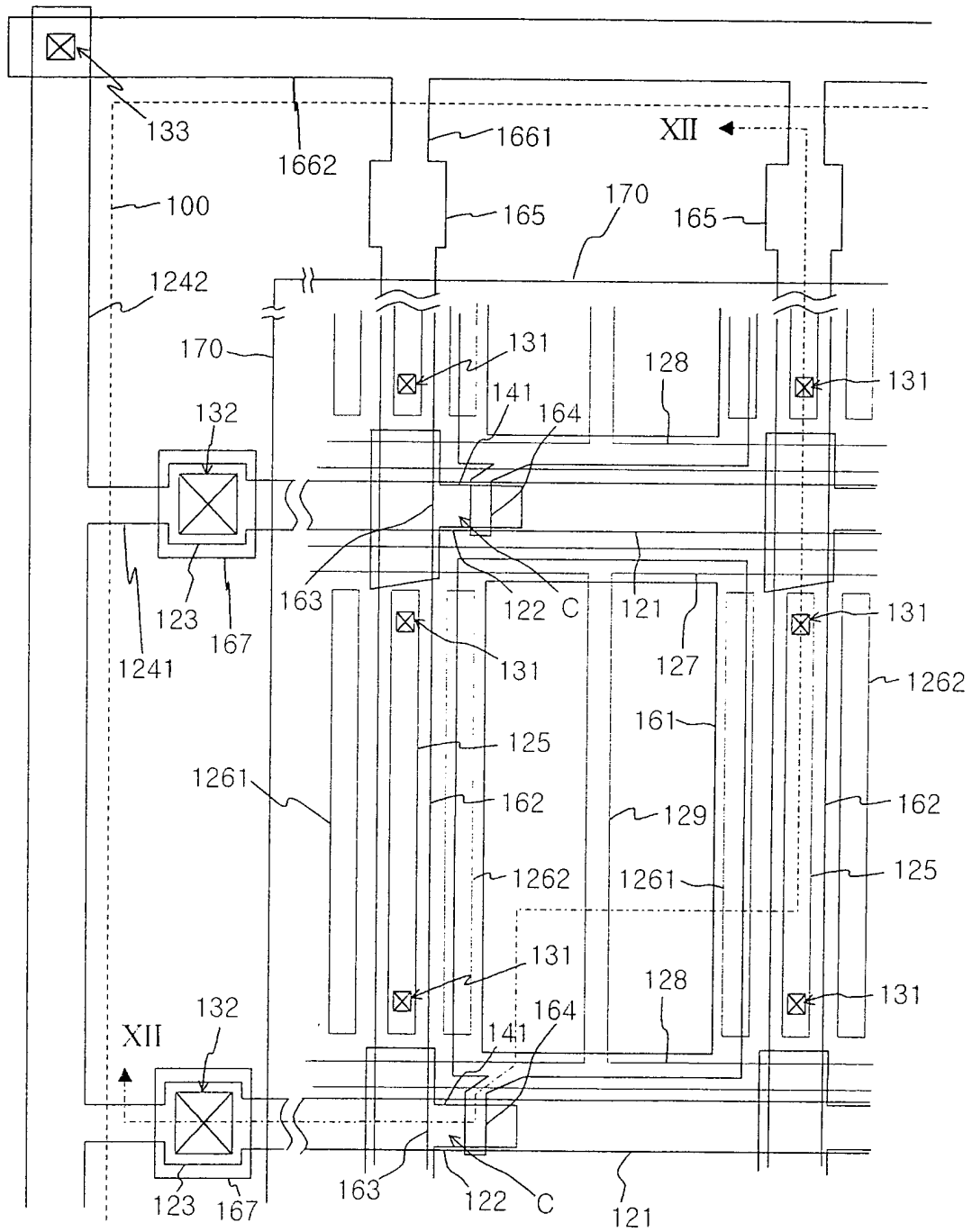


FIG.12

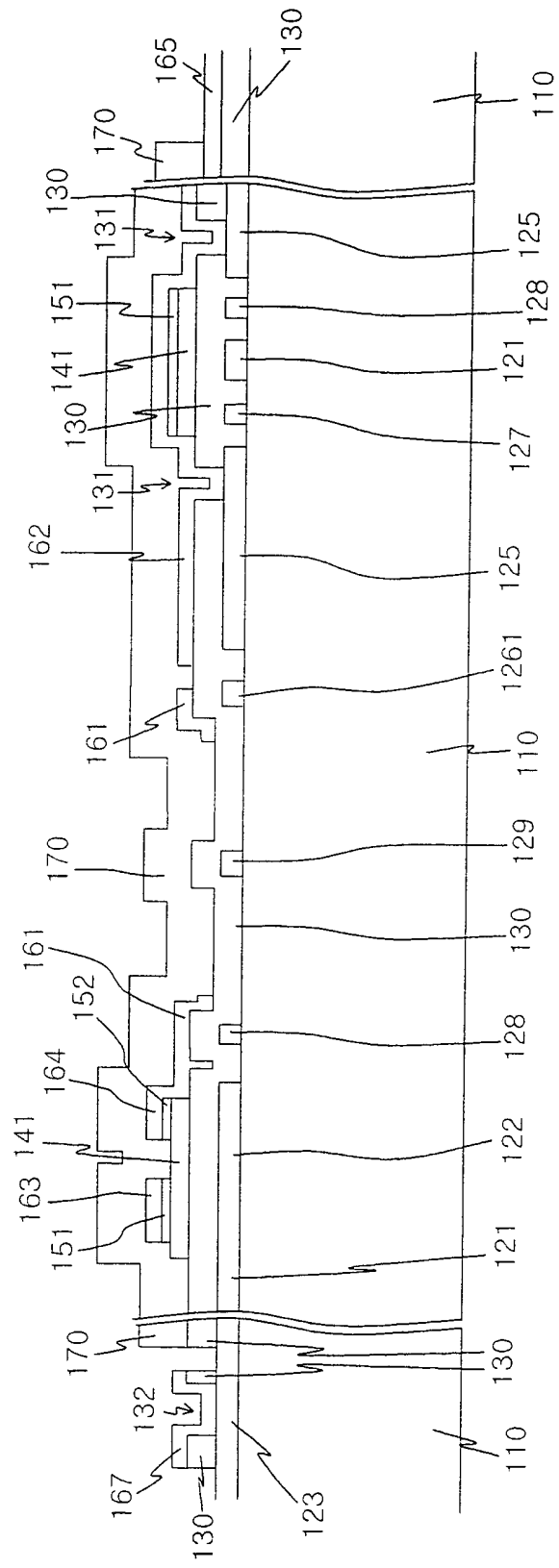


FIG.13A

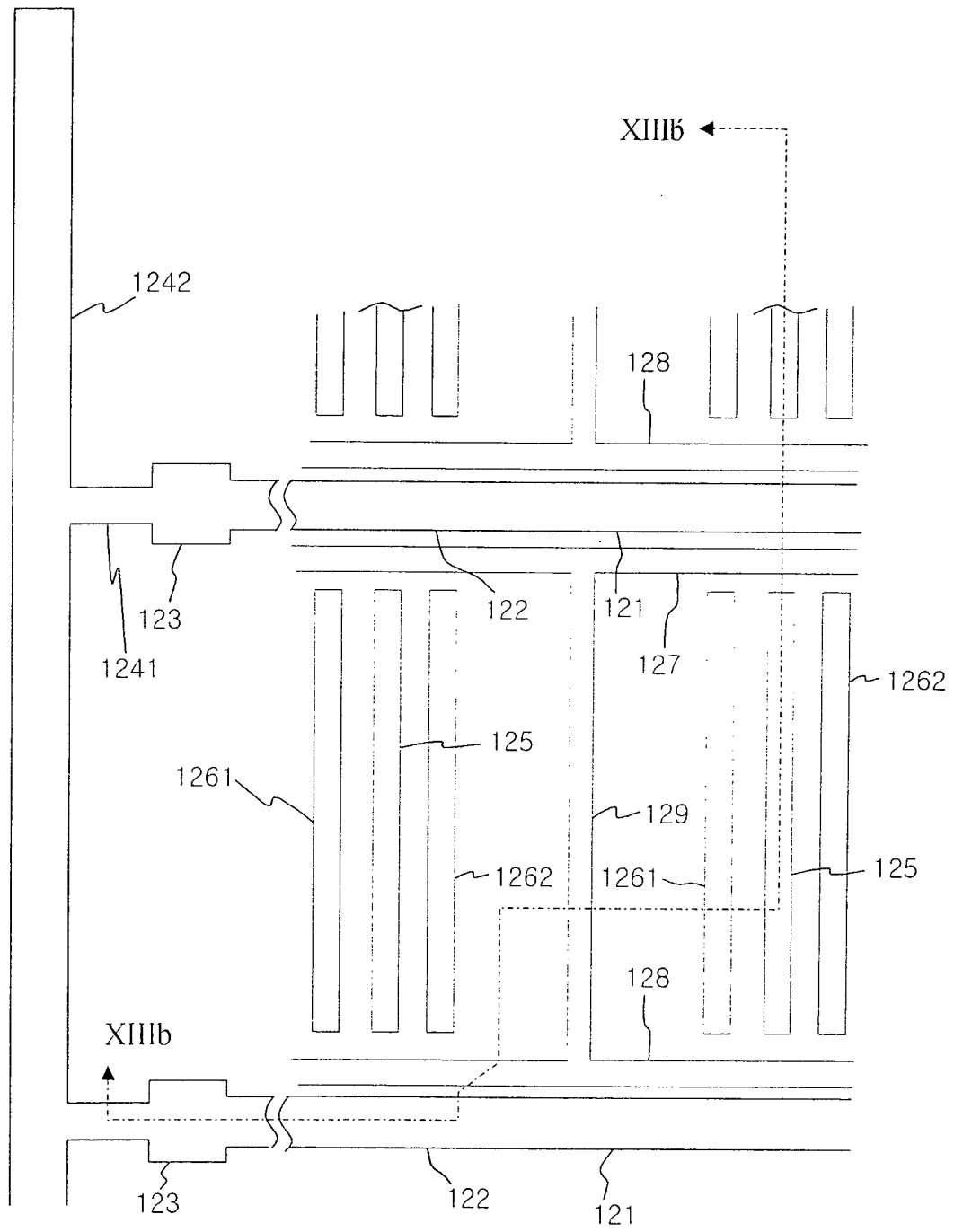


FIG. 13B

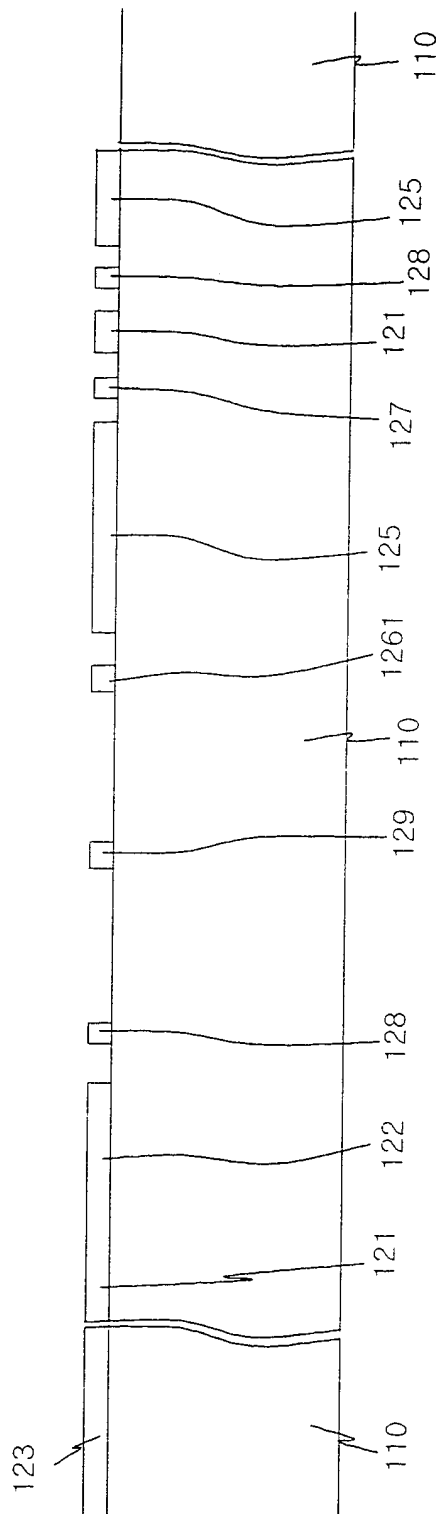


FIG. 14A

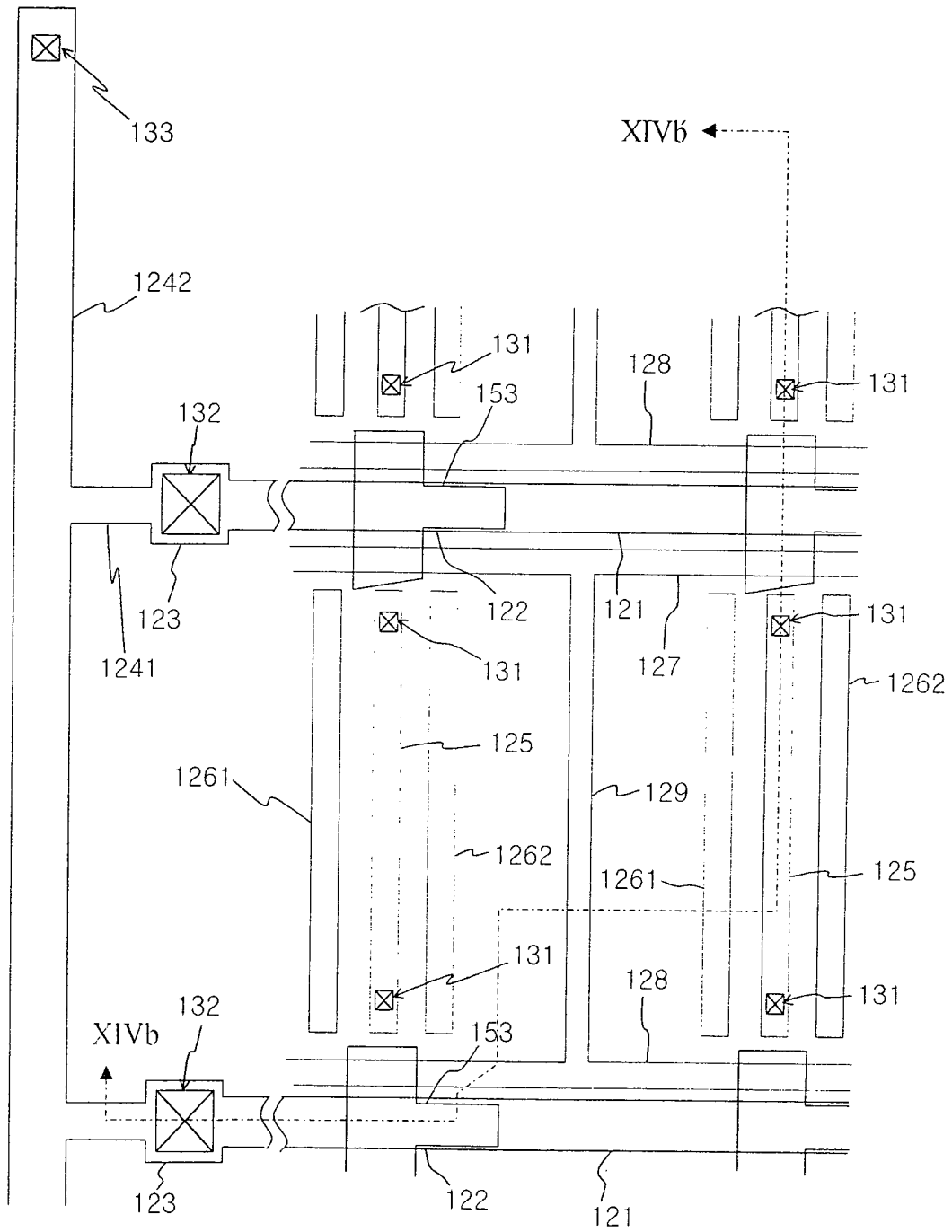


FIG. 14B

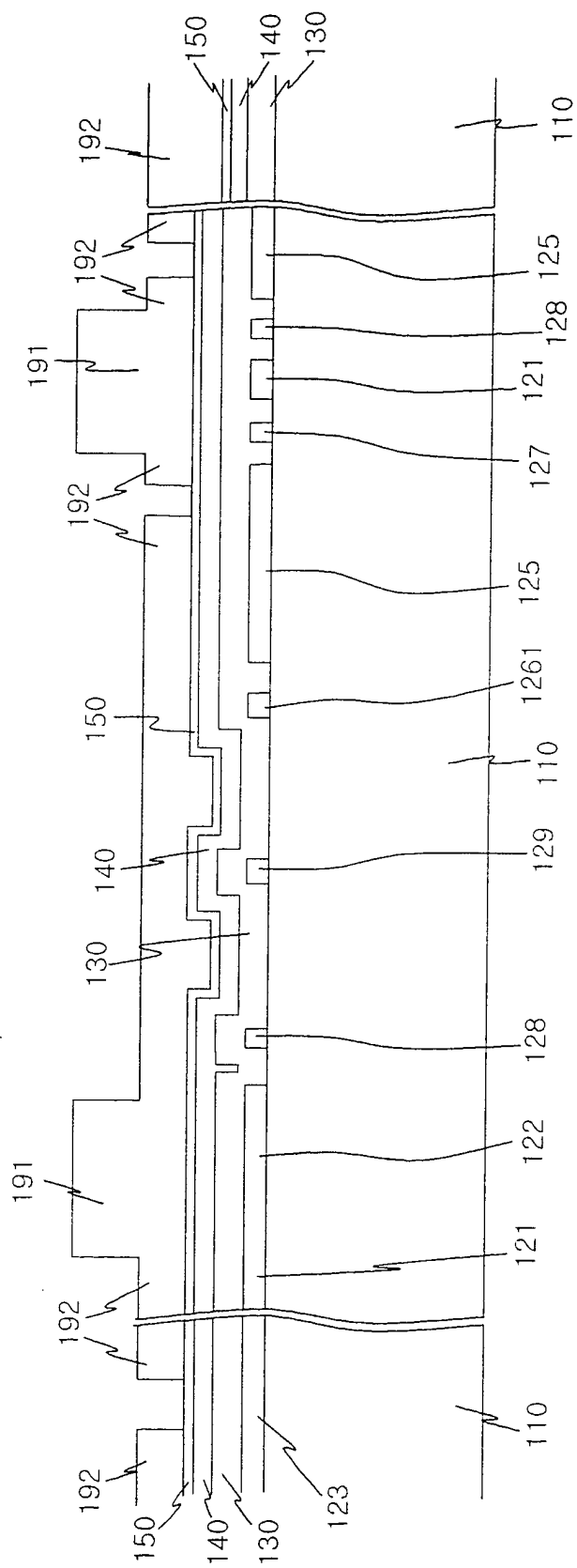


FIG.15

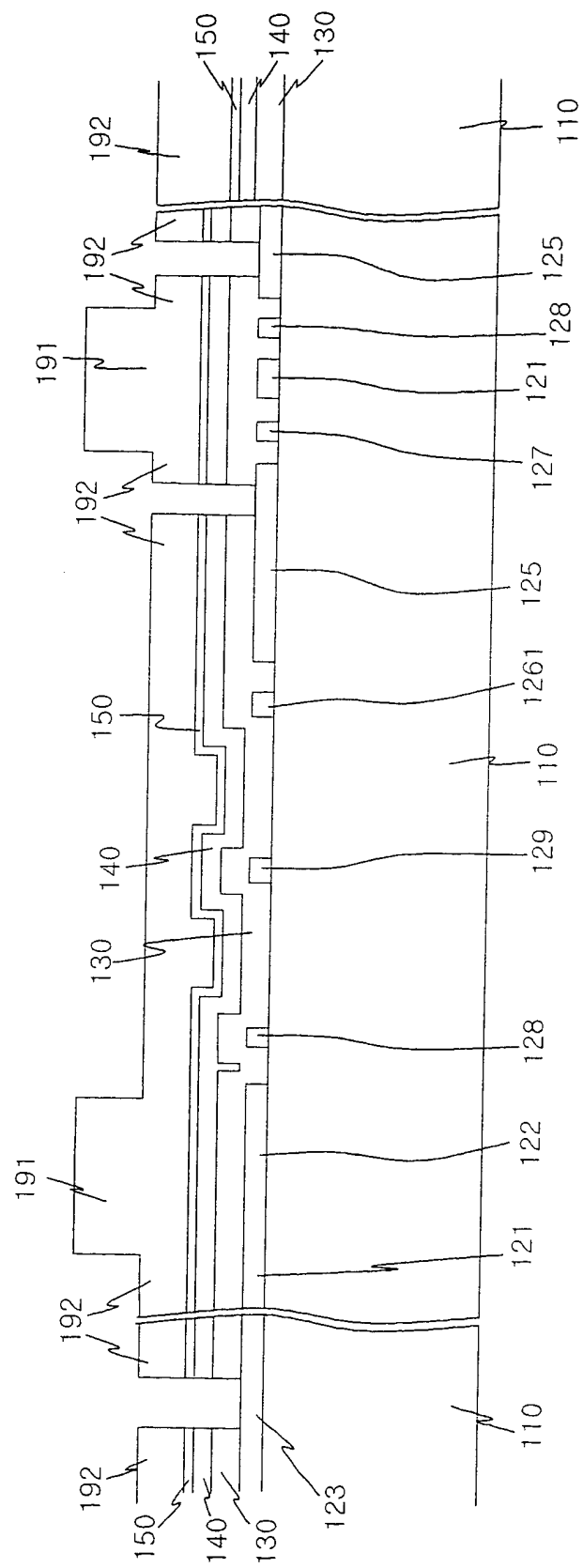


FIG. 16

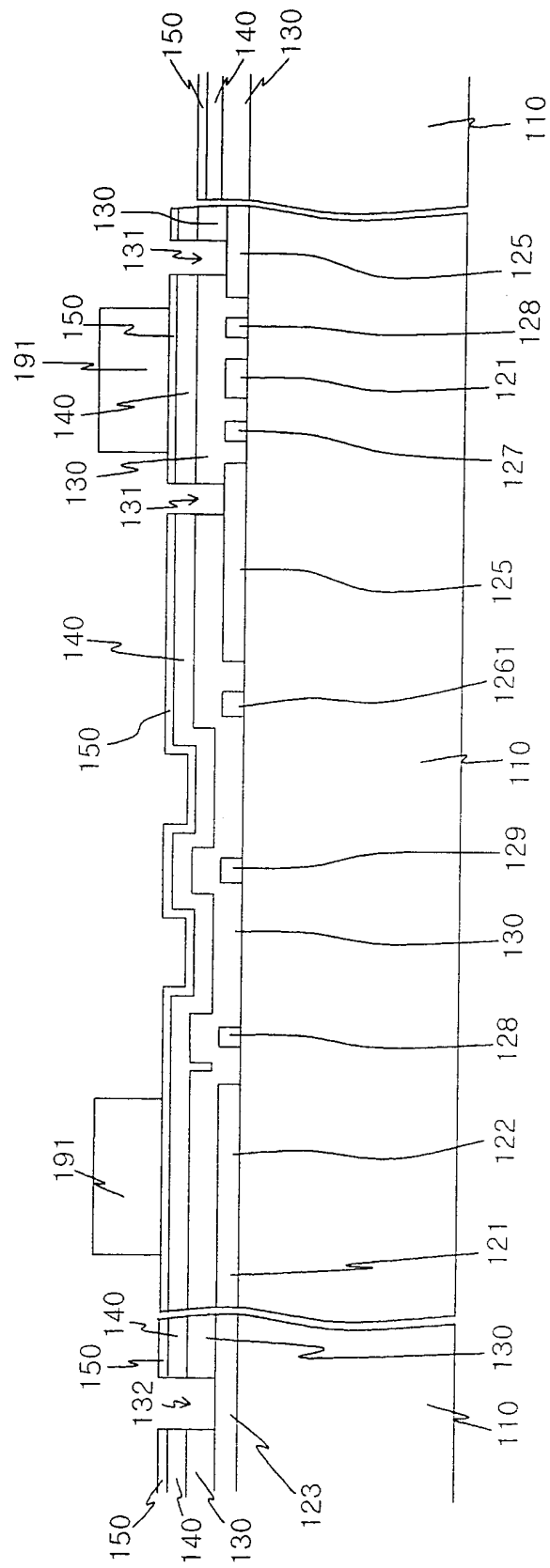


FIG.17

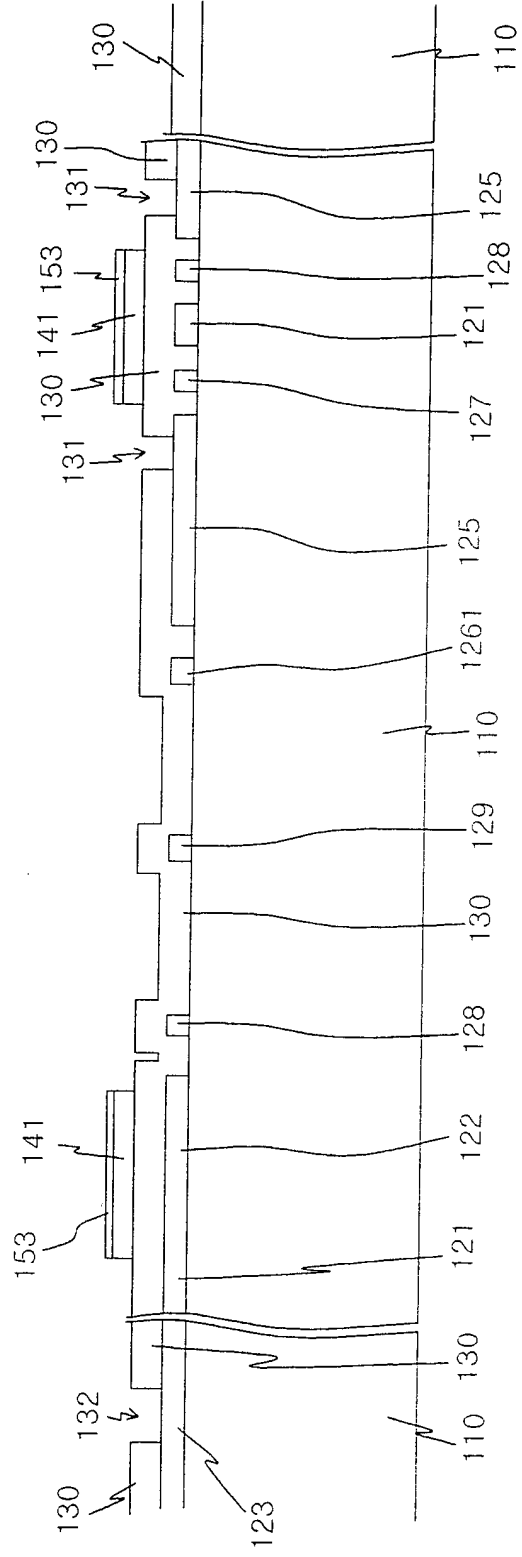


FIG.18A

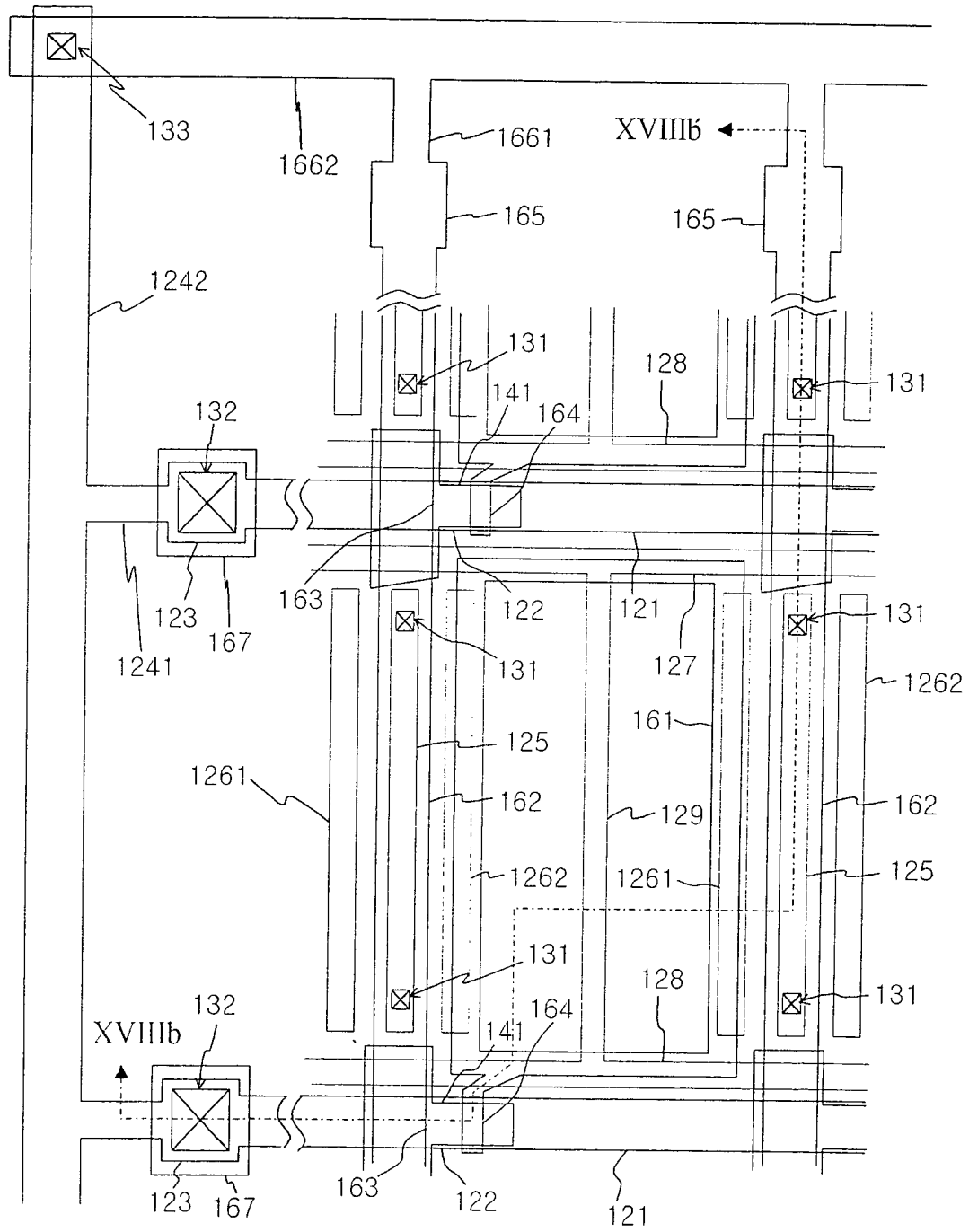


FIG. 18B

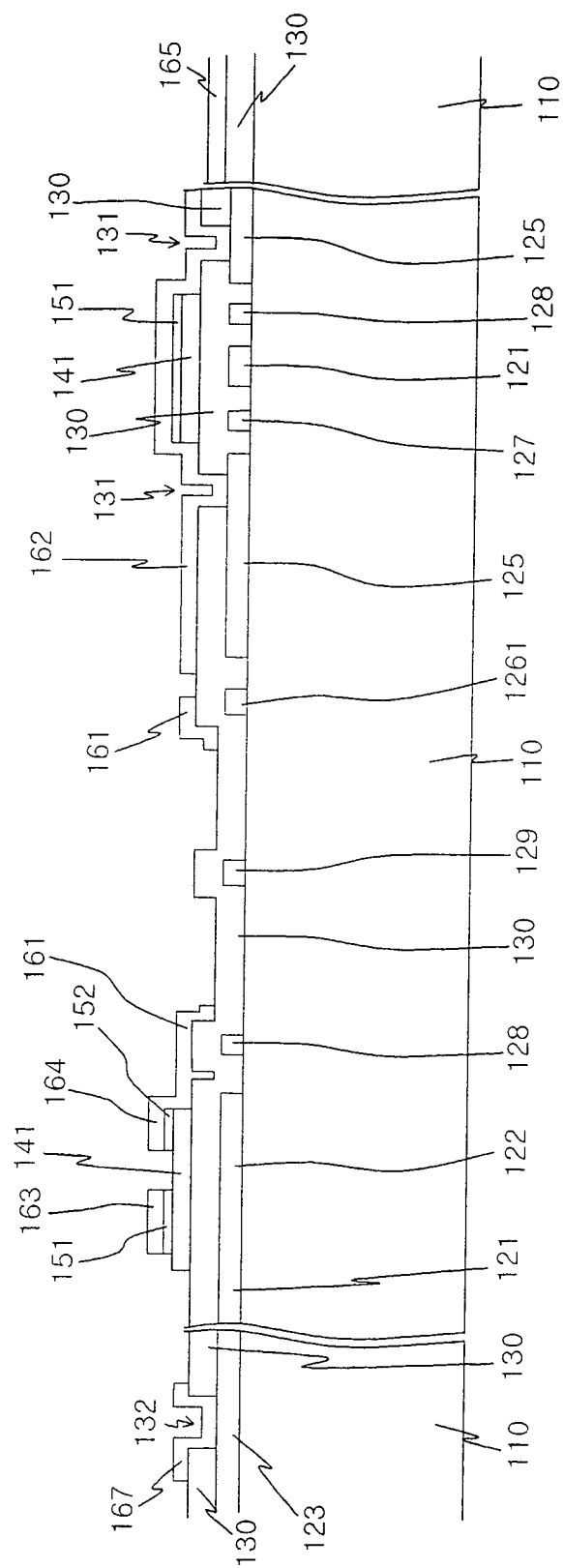


FIG. 19

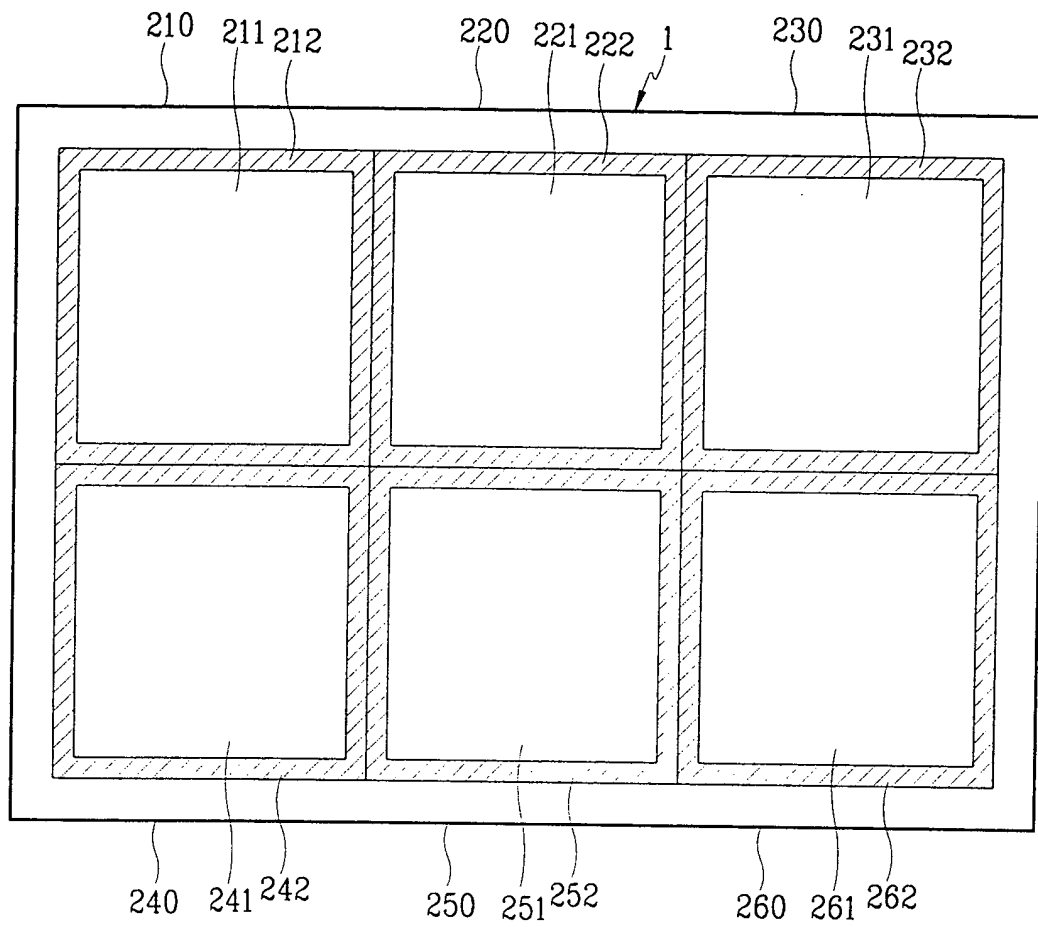


FIG. 20

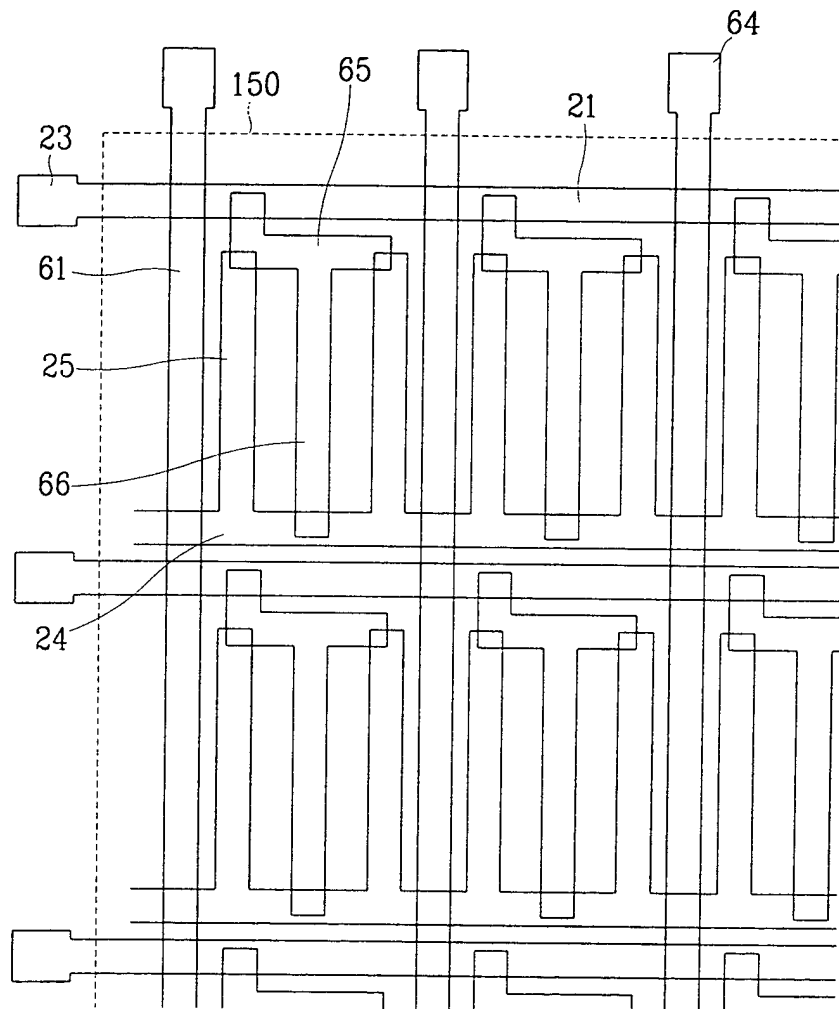


FIG. 21

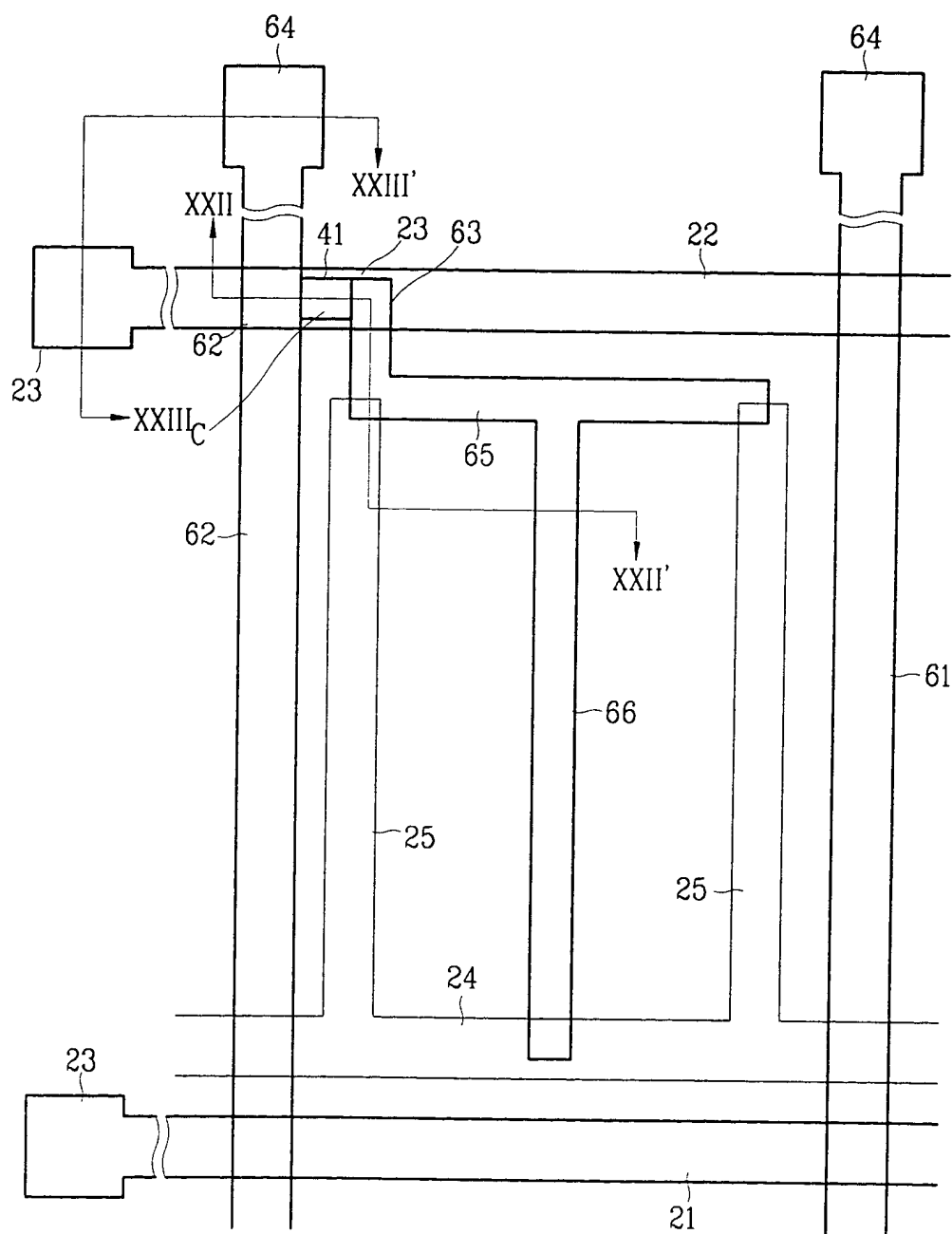


FIG. 22

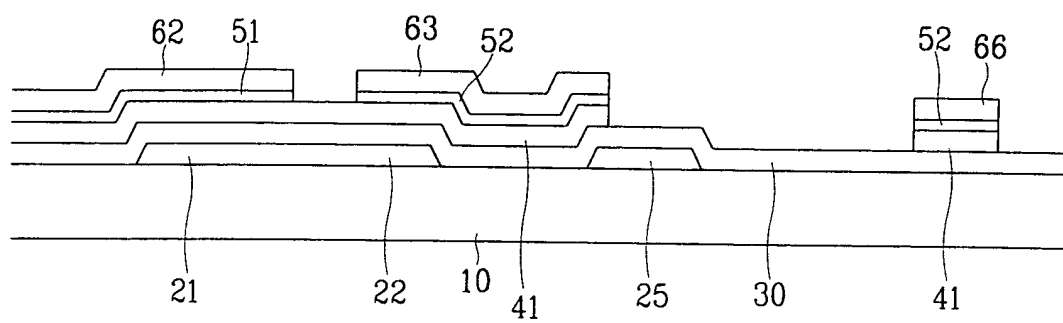


FIG. 23

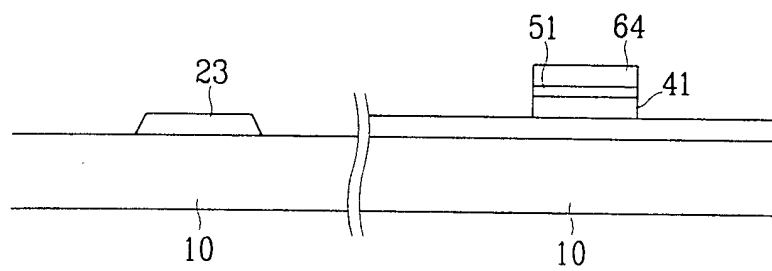


FIG. 24A

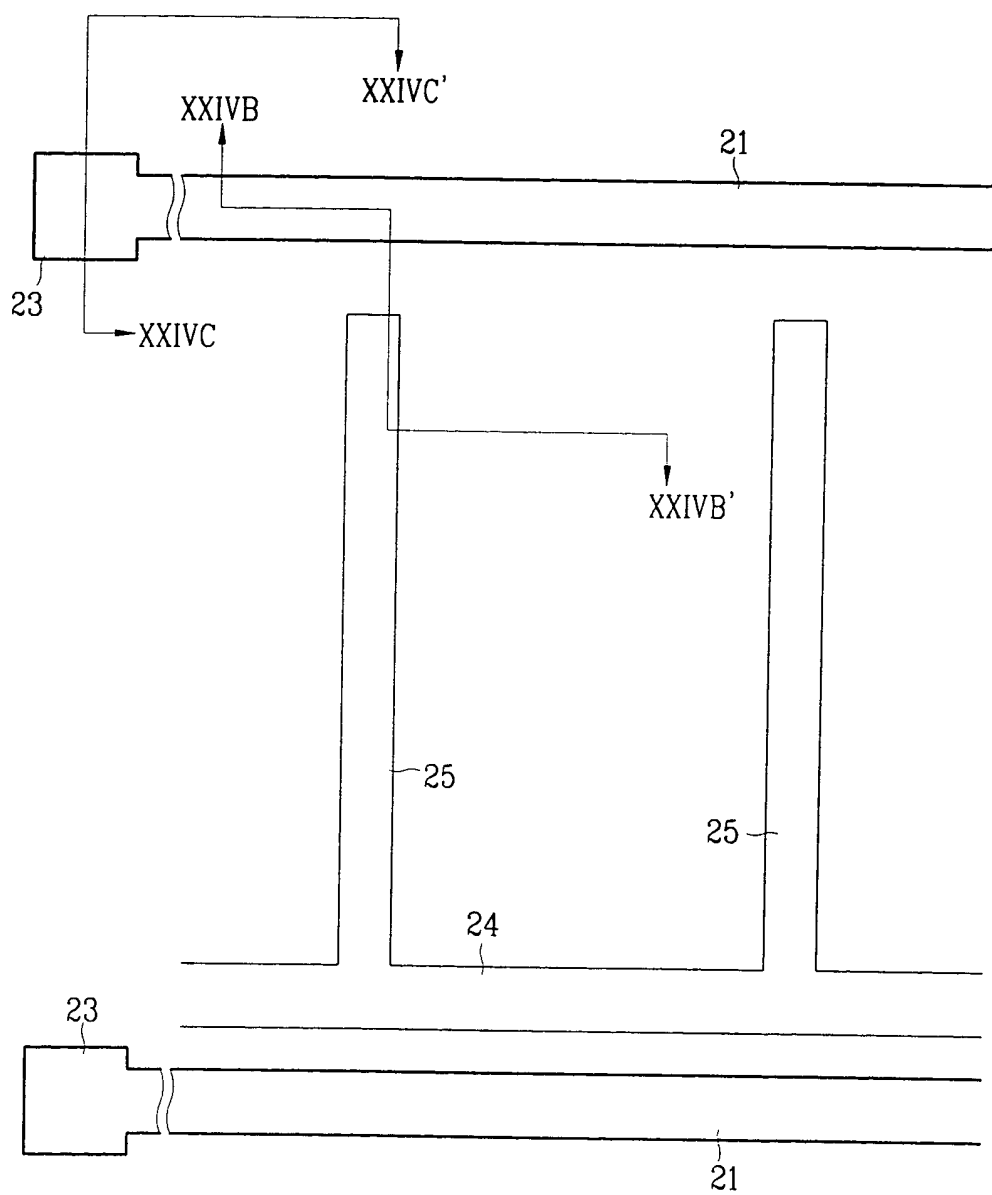


FIG. 24B

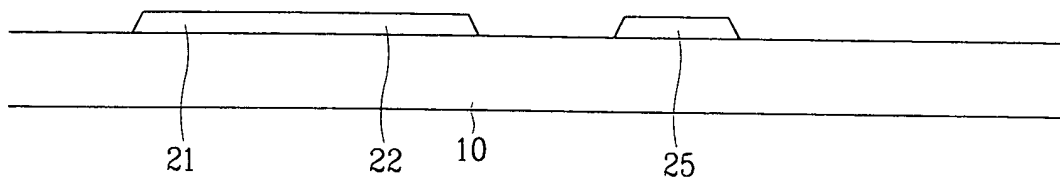


FIG. 24C

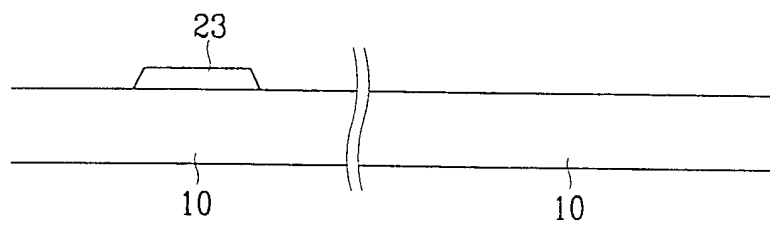


FIG. 25A

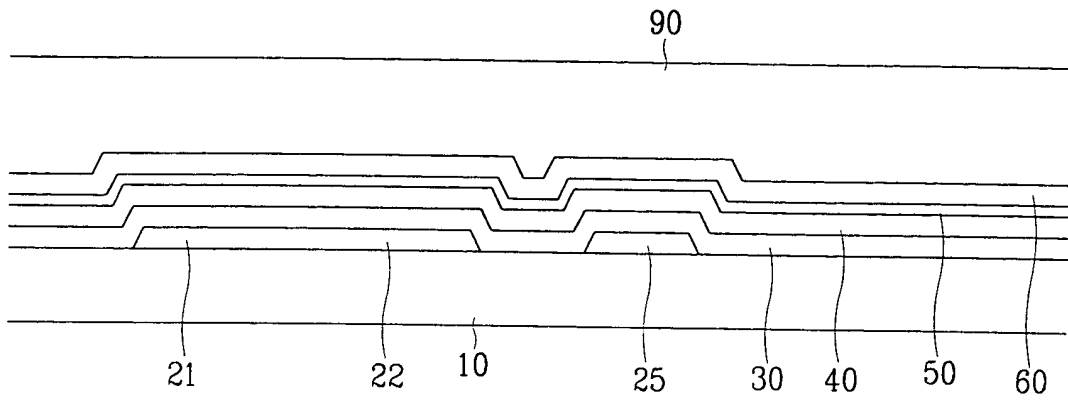


FIG. 25B

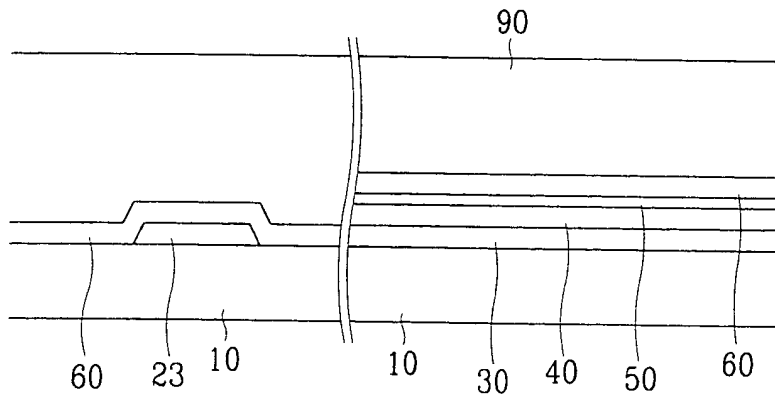


FIG. 26

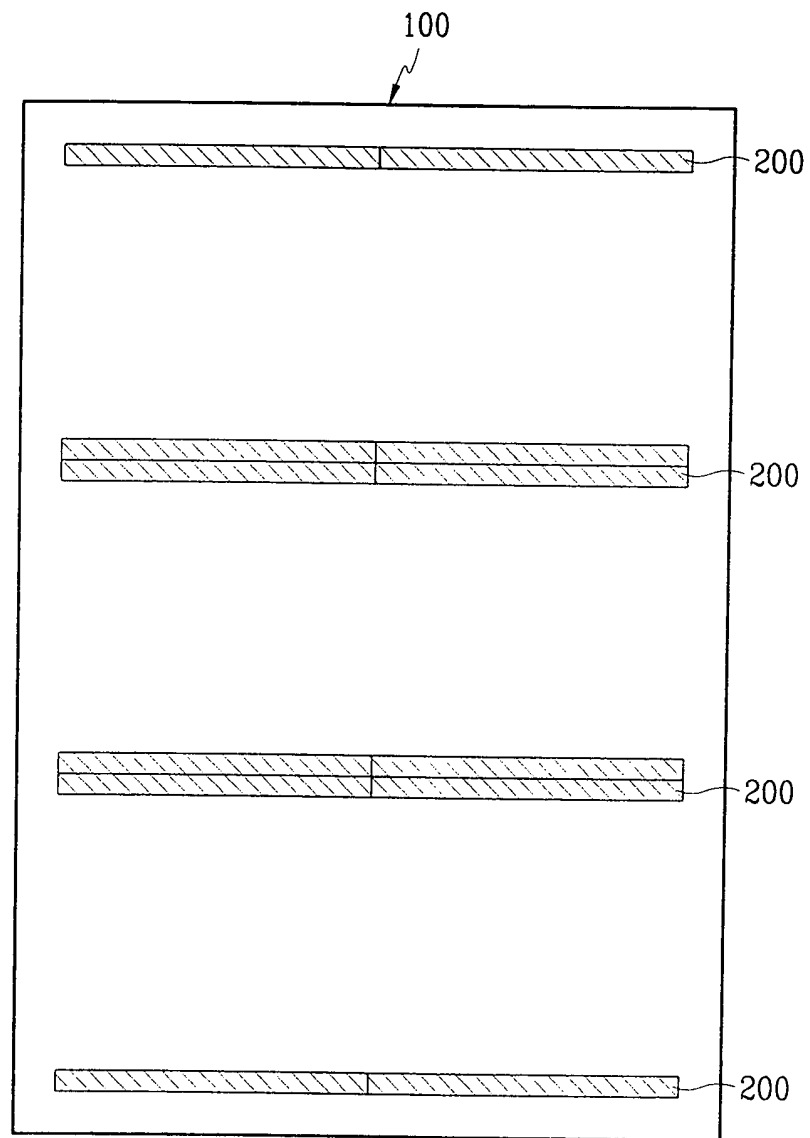


FIG. 27

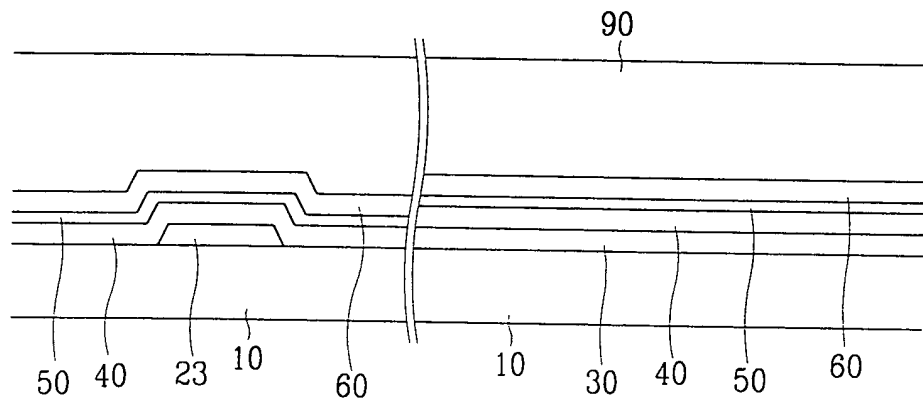


FIG. 28A

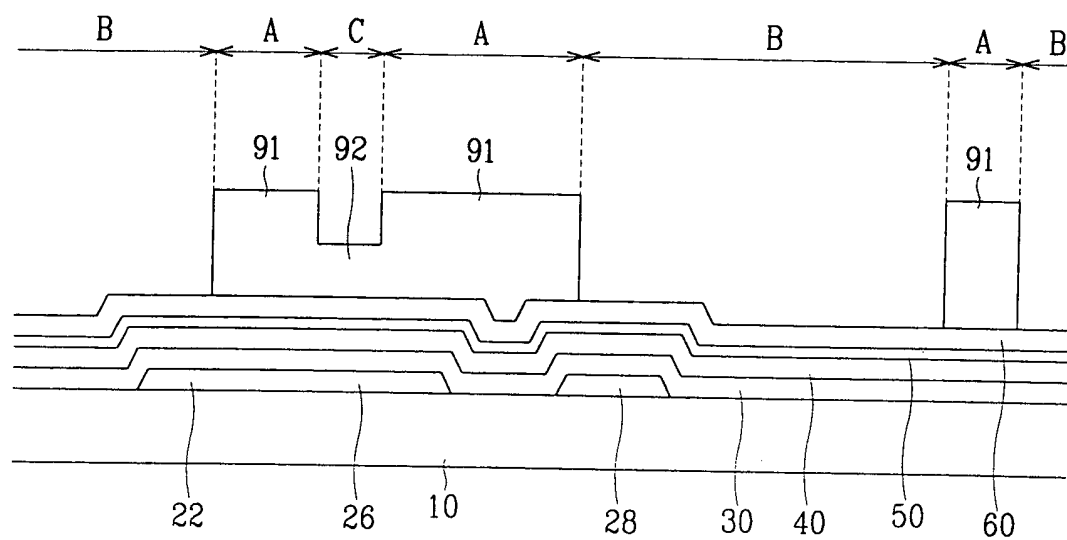


FIG. 28B

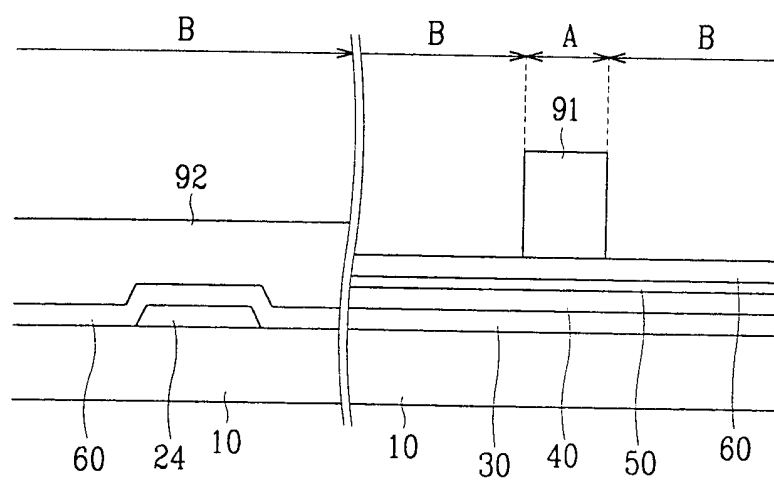


FIG. 29

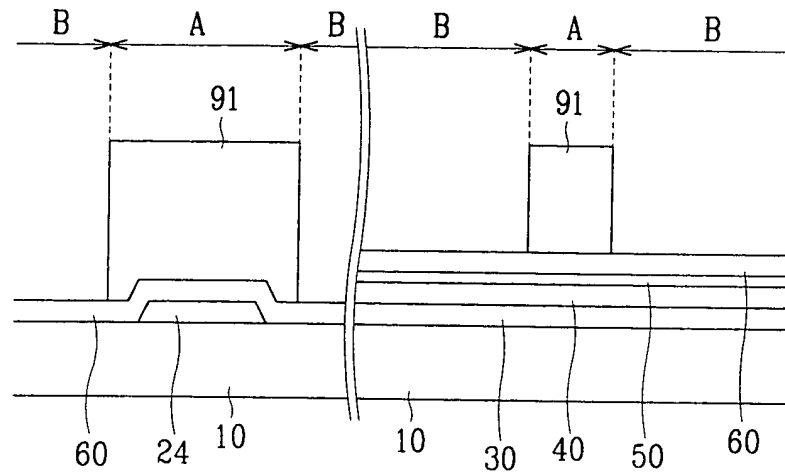


FIG. 30

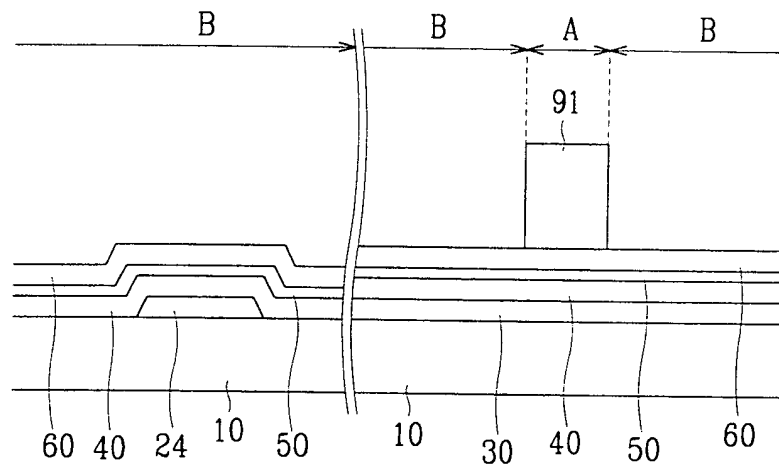


FIG. 31

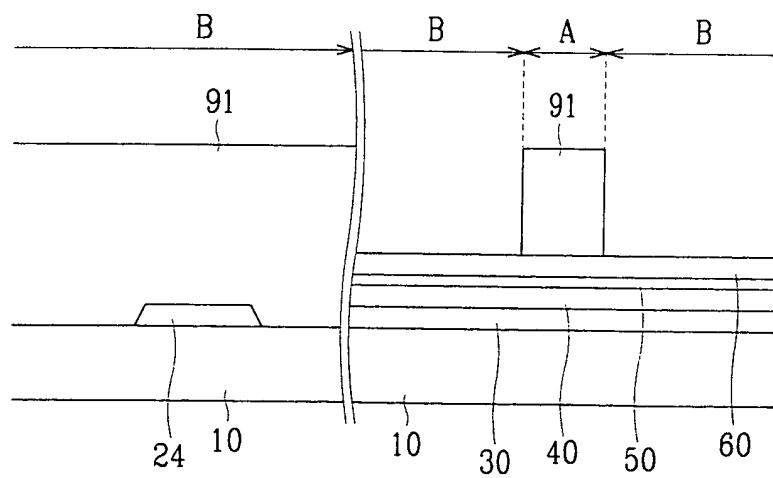


FIG. 32A

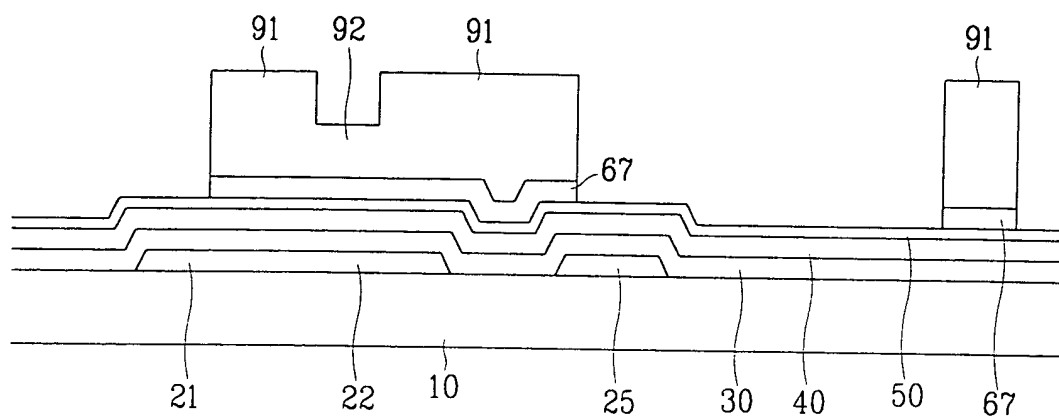


FIG. 32B

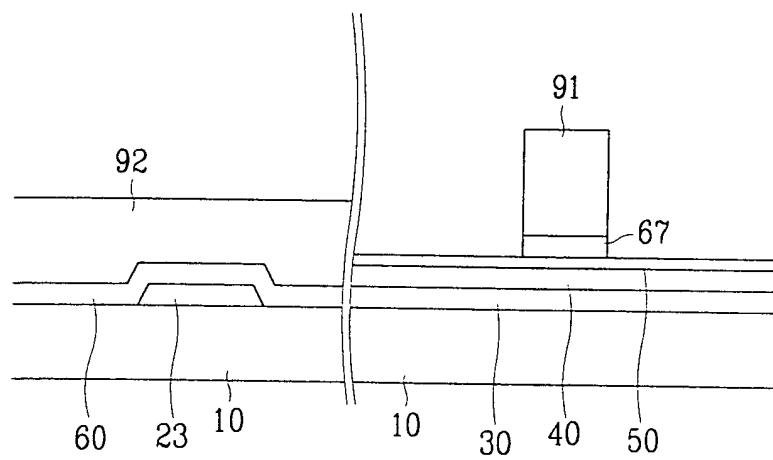


FIG. 33A

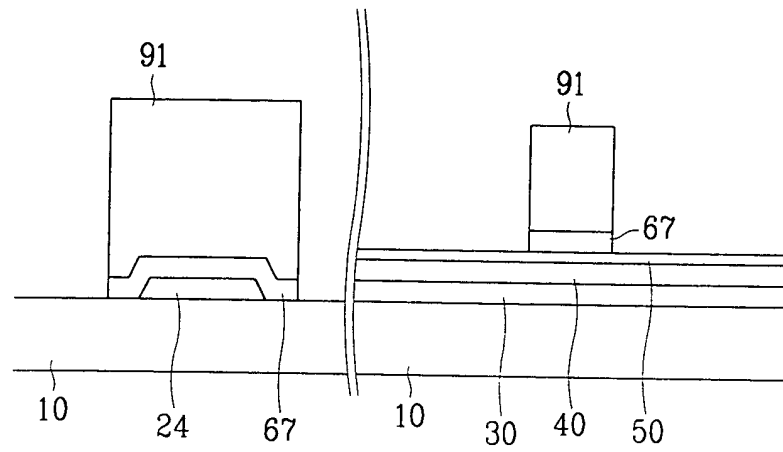


FIG. 33B

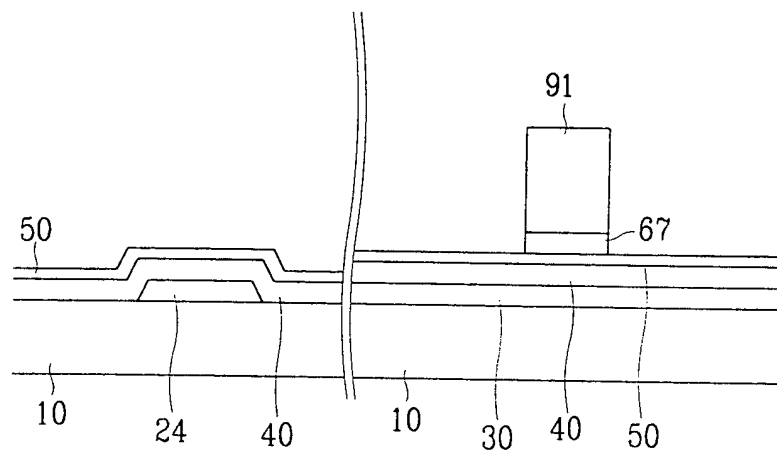


FIG. 34A

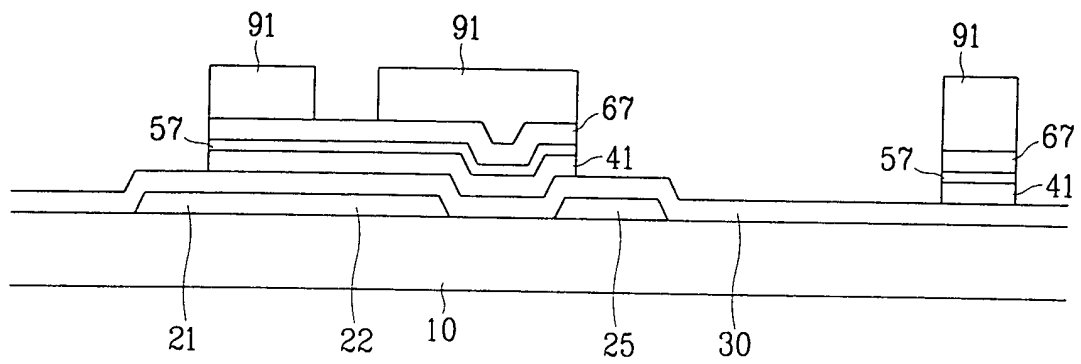


FIG. 34B

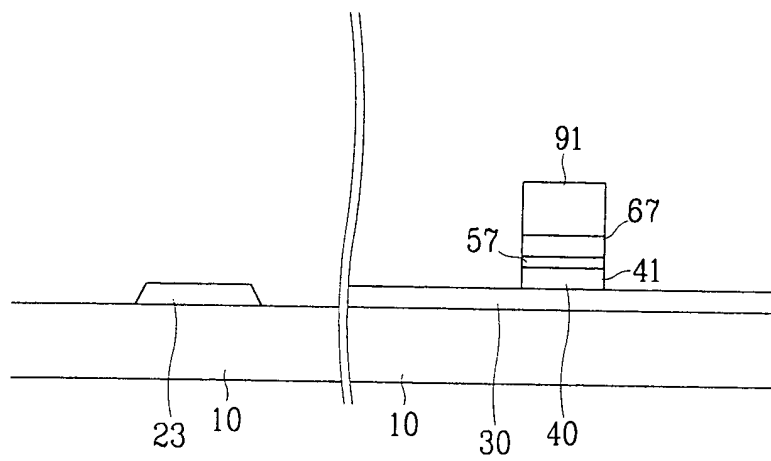


FIG. 35A

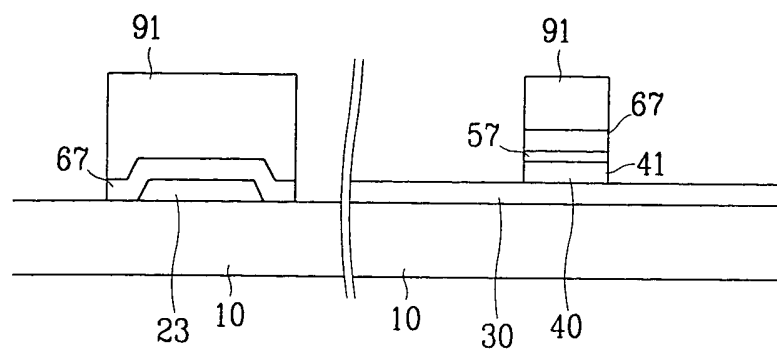


FIG. 35B

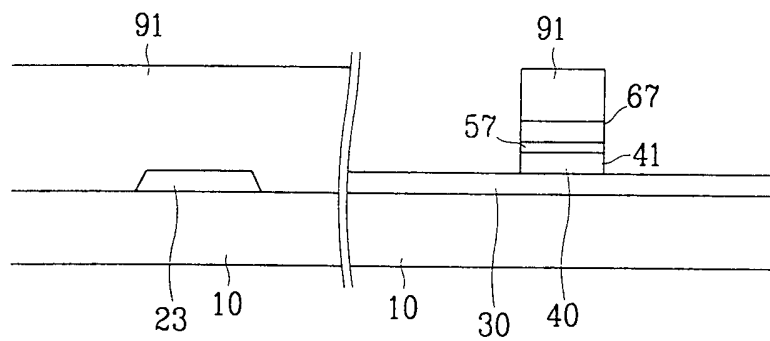


FIG. 35C

